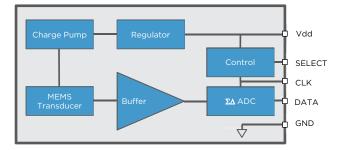
The SPH0690LM4H-1 is a miniature, high-performance, low power, bottom port silicon digital microphone with a single bit PDM output. Using Knowles' proven high performance SiSonic™ MEMS technology, the SPH0690LM4H-1 consists of an acoustic sensor, a low noise input buffer, and a sigma-delta modulator. These devices are suitable for applications such as cellphones, smart phones, laptop computers, sensors, digital still cameras, portable music recorders, and other portable electronic devices where excellent wideband audio performance and RF immunity are required. In addition, the SPH0690LM4H-1 offers multiple performance modes.



## ABSOLUTE MAXIMUM RATINGS

Table 1: Absolute Maximum Ratings

Parameter	Absolute Maximum Rating	Units
Vdd to Ground	-0.5, +5.0	V
DATA, CLOCK, SELECT to Ground	-0.3, +5.0	V
Input Current	±5	mA
Short Circuit to/from DATA	Indefinite to Ground or Vdd	sec
Storage Temperature	-40 to +100	°C
Operating Temperature	-40 to +100	°C

Stresses exceeding these "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation at these or any other conditions beyond those indicated under "Acoustic & Electrical Specifications" is not implied. Exposure beyond those indicated under "Acoustic & Electrical Specifications" for extended periods may affect device reliability.

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### PRODUCT FEATURES

- Low Distortion /High AOP
- High SNR (69dB with a 1.536MHz clock)
- Low Current Consumption in Low-Power Mode
- Flat Frequency Response
- High Drive Capability
- RF Shielded
- Bottom Port
- Sensitivity Matching
- Supports Dual Multiplexed Channels
- Multiple Performance Modes (Sleep, Low-Power, Normal)
- Ultra-Stable Performance
- Omnidirectional
- Standard SMD Reflow
- LGA Package

### TYPICAL APPLICATIONS

- Portable Electronics
- Cellphones
- Laptop Computers
- Tablets
- Digital Still Cameras
- Portable Music Recorders





## ACOUSTIC & ELECTRICAL SPECIFICATIONS<sup>1</sup>

#### Table 2: General Microphone Specifications

Test Conditions: 23 ±2°C, 55±20% R.H., Vdd=1.8 V, Tedge ≤ 3ns, unless otherwise indicated

Parameter	Symbol	Conditions	Min	Тур	Max	Units
Supply Voltage	Vdd		1.65	1.8	3.6	V
Low Frequency Rolloff	LFRO	-3dB relative to 1 kHz	-	30	-	Hz
High Frequency Flatness		+3dB relative to 1 kHz	-	14.5	-	kHz
Resonant Frequency Peak	Fres	Free Field response	-	24	-	kHz
DC Offset		Fullscale = ±100	-3.25	-	0.1	% FS
Directivity			Omnidirect	ional		
Polarity		Increasing sound pressure	Increasing	density of 1's	6	
Data Format			1/2 Cycle PE	DM		
Sensitivity Drop		$Vdd(min) \le Vdd \le Vdd(max)$	-	-	±0.25	dB
Clock Input Capacitance	Cin		-	5	-	pF
Data Output Capacitance	Cout		-	54	-	pF
Data Output Load	Cload		-	-	100	pF
SELECT (high)			Vdd-0.2	-	3.6	V
SELECT (low)			-0.3	-	0.2	V
Short Circuit Current	lsc	Grounded DATA pin	1	-	20	mA
Fall-asleep Time <sup>3,4</sup>		Fclock < 250kHz	-	-	10	ms
Wake-up Time <sup>3,5</sup>		Fclock ≥ 500kHz	-	-	35	ms
Startup Time <sup>3</sup>		Powered Down $\rightarrow$ Active, S within 1 dB of final value	- /	-	35	ms
Time to First Data Bit <sup>6</sup>		Time from valid Vdd and CLK until the first logical bit is driven on the DATA line. The output is tristate until First Data Bit.		4		ms
Mode-Change Time <sup>3, 6</sup>		Low Power Mode ⇔ Normal Mode	-		17	ms



#### Table 3: Normal Mode

Test Conditions: 23 ±2°C, 55±20% R.H., Vdd=1.8 V, Fclock = 2.4 MHz (D.C. = 50%), OSR=64, Tedge ≤ 3ns, SELECT grounded, no load, unless otherwise indicated

Parameter	Symbol	Conditions	Min	Тур	Max	Units
		Fclock = 1.2 MHz	-	650	690	
		Fclock = 1.536 MHz	-	750	820	
Supply Current <sup>2</sup>	ldd	Fclock = 2.4 MHz	800	1000	1200	μΑ
		Fclock = 3.072 MHz	-	1225	1350	
		Fclock = 4.8 MHz	-	1850	2000	
Sensitivity	S	94 dB SPL @ 1 kHz	-36	-35	-34	dBFS
		94 dB SPL @ 1 kHz, A-weighted, Fclock = 1.2 MHz	-	68.5	-	
		94 dB SPL @ 1 kHz, A-weighted, Fclock = 1.536 MHz	-	68.75	-	
Signal to Noise Ratio	SNR	94 dB SPL @ 1 kHz, A-weighted, Fclock = 2.4 MHz	-	68	-	dB(A)
		94 dB SPL @ 1 kHz, A-weighted, Fclock = 3.072 MHz	-	68	-	
		94 dB SPL @ 1 kHz, A-weighted, Fclock = 4.8 MHz	-	68	-	
Near-Ultrasonic SNR		94 dB SPL, @ 19 kHz , BW = 18.5 - 20.0 kHz	-	82	-	dB
	THD	94 dB SPL @ 1 kHz	-	0.2	0.3	%
Total Harmonic Distortion		115 dB SPL @ 1 kHz	-	0.8	-	70
		1% THD @ 1 kHz, S = typ	-	117	-	dB SPL
Acoustic Overload Point	AOP	10% THD @ 1 kHz, S = typ	-	130	-	dB SPL
Power Supply Rejection Ratio	PSRR	200 mVpp sinewave @ 1 kHz	-	84	-	dB V/FS
Power Supply Rejection	PSR+N	200 mVpp 7/8 duty cycle rectangular waveform @ 217 Hz, A-weighted	-	-98	-	dBFS(A)

#### Table 4: Low-Power Mode

Test Conditions: 23 ±2°C, 55±20% R.H., Vdd=1.8 V, Fclock = 768 kHz (D.C. = 50%), OSR=48, Tedge ≤ 3ns, SELECT grounded, no load, unless otherwise indicated

Parameter	Symbol	Conditions	Min	Тур	Max	Units
Supply Current <sup>2</sup>	ldd		240	260	310	μA
Sensitivity	S	94 dB SPL @ 1 kHz	-22	-21	-20	dBFS
Signal to Noise Ratio	SNR	94 dB SPL @ 1 kHz, A-weighted (BW = 8 kHz)	-	66	-	dB(A)
Total Harmonia Distartion	THD	94 dB SPL @ 1 kHz	-	0.2	0.3	%
Total Harmonic Distortion		1% THD @ 1 kHz, S = typ	-	113	-	dB SPL
Acoustic Overload Point	AOP	10% THD @ 1 kHz, S = typ	-	116	-	dB SPL
Power Supply Rejection Ratio	PSRR	200 mVpp sinewave @ 1 kHz	-	77	-	dBV/FS
Power Supply Rejection	PSR+N	200 mVpp 7/8 duty cycle rectangular waveform @ 217 Hz, A-weighted	-	-86	-	dBFS(A)





#### Table 5: Sleep Mode

Test Conditions: 23 ±2°C, 55±20% R.H., Vdd=1.8 V, Fclock = 0 Hz, SELECT grounded, no load, unless otherwise indicated

Parameter	Symbol	Conditions	Min	Тур	Max	Units
Sleep Current	Isleep		-	40	55	μΑ

<sup>1</sup> Sensitivity and Supply Current are 100% tested.

<sup>2</sup> Idd varies with Cload according to:  $\Delta$ Idd = 0.5\*Vdd\* $\Delta$ Cload\*Fclock.

<sup>3</sup> Valid microphones states are: Powered Down Mode (mic off), Sleep Mode (low current, DATA = high-Z, fast startup), Low-Power Mode (low clock speed) and Normal Mode.

<sup>4</sup> Time from Fclock < 250 kHz to Isleep specification is met when transitioning from Active Mode to Sleep Mode.

<sup>5</sup> Time from Fclock ≥ 500 kHz to all applicable specifications are met when transitioning from Sleep Mode to Active Mode.

<sup>6</sup> Audio is temporarily muted during the transition between any microphone state.

#### Table 6: Digital Interface

Test Conditions: 23 ±2°C, 55±20% R.H., Vdd=1.8 V, Tedge ≤ 3ns, unless otherwise indicated

Parameter	Symbol	Conditions	Min	Тур	Мах	Units
Logic Input High <sup>7</sup>	Vih		0.65xVdd	-	3.6	V
Logic Input Low <sup>7</sup>	Vil		-0.3	-	0.35xVdd	V
Logic Output High <sup>7</sup>	Voh	I <sub>OUT</sub> = 2 mA	Vdd-0.45	-	Vdd	V
Logic Output Low <sup>7</sup>	Vol	I <sub>OUT</sub> = 2 mA	0	-	0.45	V
Low→High Threshold <sup>8</sup>	VI-h		-	-	0.65xVdd	V
High→Low Threshold <sup>8</sup>	Vh-l		0.35xVdd	-	-	V
Hysteresis Width <sup>8</sup>	Vhyst		0.05xVdd	-	0.20xVdd	V
		Sleep Mode	0	-	250	Let 1
Clock Frequency <sup>7</sup>	Fclock	Low-Power Mode	500	-	900	kHz
		Normal Mode	1.1	-	4.8	MHz
Clock Duty Cycle	D.C.		40	50	60	%
Delay Time to Data Line Driven <sup>7</sup>	Tdd		18	-	35	ns
Delay Time to Valid Data <sup>7</sup>	Tdv	Max Cload	-	-	100	ns
Delay Time to High Z <sup>7</sup>	Tdz		5	-	16	ns
Hold Time <sup>7</sup>	Thold	Thold, as observed by the input device, will be dependent on Cload	5	-		ns

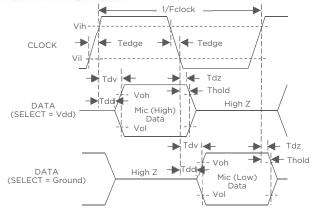
<sup>7</sup> See Figure 1: Timing Diagram.

<sup>8</sup> See Figure 2: Hysteresis Diagram.

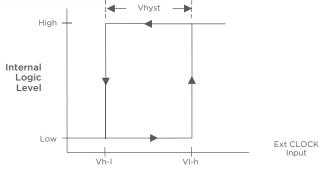




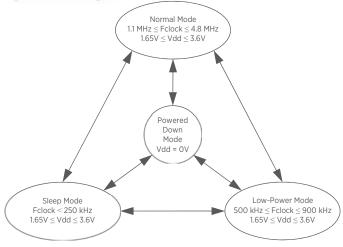
#### Figure 1: Timing Diagram



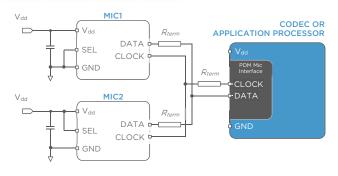
#### Figure 2: Hysteresis Diagram



#### Figure 3: State Diagram



#### Figure 4: Typical Application Circuit



#### NOTES

All Ground pins must be connected to ground.

Bypass capacitors should be placed next to each Vdd pin for best performance. Capacitors near the microphone should not contain Class 2 dielectrics due to their piezoelectric effect.

#### Table 7: SELECT Functionality

Microphone	SELECT	Asserts DATA on	Latch DATA on
Mic (High)	Vdd	CLK rising edge	CLK falling edge
Mic (Low)	Ground	CLK falling edge	CLK rising edge



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## PERFORMANCE CURVES

Test Conditions: 23 ±2°C, 55±20% R.H., Vdd=1.8 V, Fclock = 2.4 MHz, SELECT grounded, no load, unless otherwise indicated



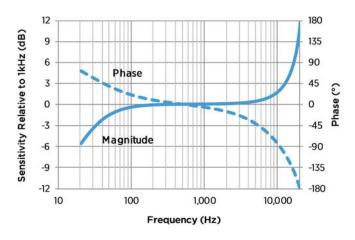
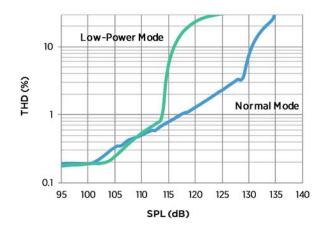
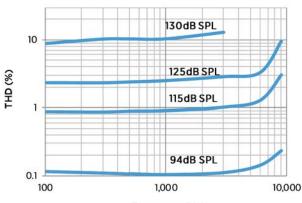


Figure 7: Typical THD vs SPL

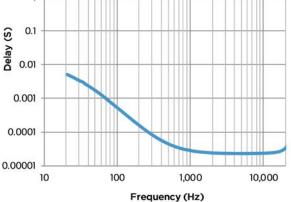


#### Figure 8: Typical THD vs Frequency



Frequency (Hz)

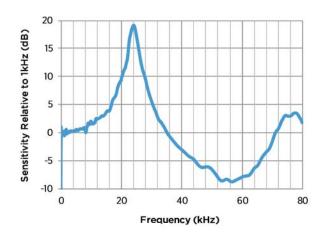
Figure 6: Typical Group Delay



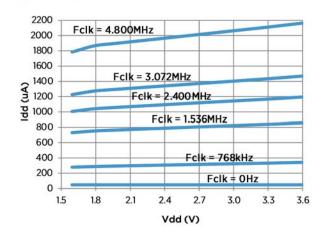


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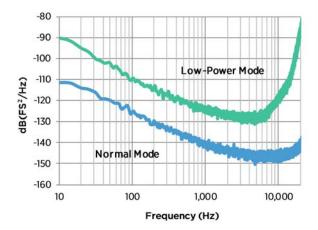
#### Figure 9: Typical Free Field Ultrasonic Response



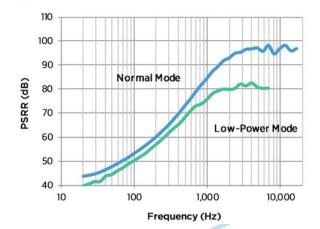
#### Figure 10: Typical Idd vs Vdd



#### Figure 11: Noise Floor Power Spectral Density

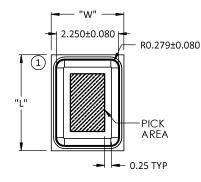


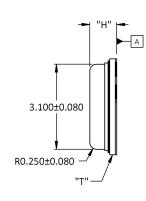
#### Figure 12: Typical PSRR

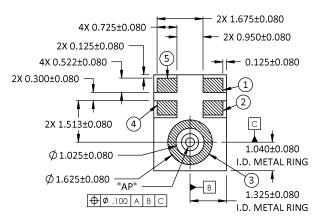




## MECHANICAL SPECIFICATIONS



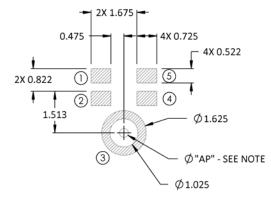




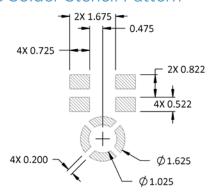
Item	Dimension	Tolerance
Length (L)	3.5	±0.10
Width (W)	2.65	±0.10
Height (H)	0.98	±0.10
Acoustic Port (AP)	Ø0.325	±0.05
PCB Thickness (T)	0.307	±0.05

Pin #	Pin Name	Туре	Description
1	DATA	Digital O	PDM Output
2	SELECT	Digital I	Lo/Hi (L/R) Select Connect to Vdd or GND
3	GROUND	Power	Ground
4	CLOCK	Digital I	Clock Input
5	Vdd	Power	Power Supply

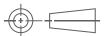
## **Example Land Pattern**



## Example Solder Stencil Pattern



#### NOTES:



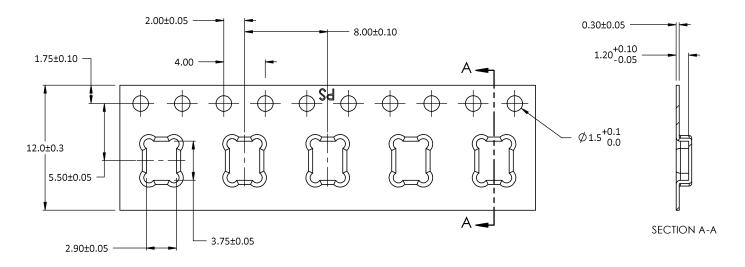
Pick Area only extends to 0.25 mm of any edge or hole unless otherwise specified. Dimensions are in millimeters unless otherwise specified. Tolerance is  $\pm 0.15$ mm unless otherwise specified In the acoustic path, the recommended PCB Hole Diameter is  $0.6 \le D \le 1.0$ mm, the recommended Ga

In the acoustic path, the recommended PCB Hole Diameter is  $0.6 \le D \le 1.0$  mm, the recommended Gasket Cavity Diameter is  $D \ge 1.0$  mm and the recommended Case Hole Diameter is  $1.0 \le D \le 1.5$  mm. Further optimizations based on application should be performed.



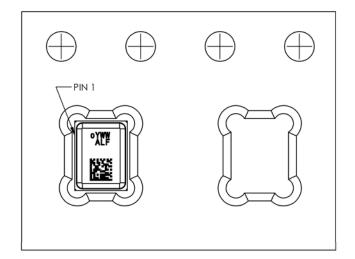


## PACKAGING & MARKING DETAIL



Model Number	Suffix	Reel Diameter	Quantity Per Reel
SPH0690LM4H-1	-8	13"	5900

Component	Surface Resistance (ohms)
Reel	10 <sup>5</sup> - 10 <sup>9</sup>
Carrier Tape	10 <sup>5</sup> - 10 <sup>9</sup>
Cover Tape	10 <sup>4</sup> - 10 <sup>10</sup>



#### NOTES:

Dimensions are in millimeters unless otherwise specified.

Vacuum pickup only in the pick area indicated in Mechanical Specifications. Tape & reel per EIA-481.

Labels applied directly to reel and external package.

Shelf life: Twelve (12) months when devices are stored in the factory-supplied, unopened ESD moisture sensitive bag under the maximum environmental conditions of 30°C, 70% R.H.

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2D barcode "ABCDEFGHJKLMNPQRSTUVWXYZ0123456789" Unique Job Identification Number for product traceability

Letter: "o", orientation mark (pin 1)

"M": Knowles Factory KEM3 "C": Knowles Factory KES2 "P": Knowles KEI

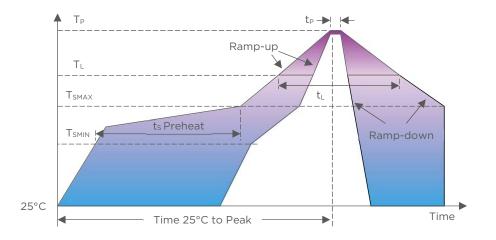
Date Code YWW: "Y": Last digit of year "WW": Work week AA = Project Name Designator:

"AL": Everest F = Factory Location:





## RECOMMENDED REFLOW PROFILE



Profile Feature	Pb-Free
Average Ramp-up rate ( $T_{\text{SMAX}}$ to $T_{\text{P}}$ )	3°C/second max.
Preheat Temperature Min (T <sub>SMIN</sub> )   • Temperature Max (T <sub>SMAX</sub> )   • Time (T <sub>SMIN</sub> to T <sub>SMAX</sub> ) (t <sub>S</sub> )	150°C 200°C 60-180 seconds
Time maintained above: • Temperature (T <sub>L</sub> ) • Time (t <sub>L</sub> )	217°C 60-150 seconds
Peak Temperature (T <sub>P</sub> )	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down rate (T <sub>P</sub> to $T_{SMAX}$ )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max

d on IPC/JDEC J-STD-020 Revision C.

emperatures refer to topside of the package, sured on the package body surface.

actual reflow profile used should be optimized based ne reflow requirements of all components, board gn, solder paste formulation and reflow equipment . Details of recommended handling and ufacturing processes can be found in AN25 SMT ufacturing Guidelines for SiSonic™ Microphones.

- (A) MSL (moisture sensitivity level) Class 1.
- (B) Maximum of 3 reflow cycles is recommended.
- (C) In order to minimize device damage:
  - Do not board wash or clean after the reflow process. .
  - Do not brush board with or without solvents after the reflow process.
  - Do not directly expose to ultrasonic processing, welding, or cleaning. .
  - Do not insert any object in port hole of device at any time.
  - Do not apply over 30 psi of air pressure into the port hole.
  - Do not pull a vacuum over port hole of the microphone.
  - Do not apply a vacuum when repacking into sealed bags at a rate faster than 0.5 atm/sec.
  - Do not directly expose to vapor phase soldering.





## MATERIALS STATEMENT

Meets the requirements of the European RoHS directive 2011/65/EC as amended.

Meets the requirements of the industry standard IEC 61249-2-21:2003 for halogenated substances and Knowles Green Materials Standards Policy section on Halogen-Free.

Product is Beryllium Free according to limits specified on the Knowles Hazardous Material List (HSL for Products).

Ozone depleting substances are not used in the product or the processes used to make the product, including compounds listed in Annex A, B, and C of the "Montreal Protocol on Substances That Deplete the Ozone Layer.

## RELIABILITY SPECIFICATIONS

Test	Description	
Thermal Shock	100 cycles of air-air thermal shock from -40°C to +125°C with 15 minute soaks (IEC 68-2-4)	
High Temperature Storage	+105°C environment for 1,000 hours (IEC 68-2-2 Test Ba)	
Low Temperature Storage	-40°C environment for 1,000 hours (IEC 68-2-1 Test Aa)	
High Temperature Bias	+105°C environment while under bias for 1,000 hours (IEC 68-2-2 Test Ba)	
Low Temperature Bias	-40°C environment while under bias for 1,000 hours (IEC 68-2-1 Test Aa)	
Temperature/Humidity Bias	+85°C/85% R.H. environment while under bias for 1,000 hours (JESD22-A101A-B)	
Vibration	12 minutes in each X, Y, Z axis from 20 to 2,000 Hz with peak acceleration of 20 G (MIL 883E, Method 2007.2,A)	
ESD-HBM	3 discharges at ±2kV direct contact to I/O pins (ESD STM5.2)	
ESD-LID/GND	3 discharges at $\pm$ 8kV direct contact to lid when unit is grounded (IEC 61000-4-2)	
Reflow	5 reflow cycles with peak temperature of +260°C	
Mechanical Shock	3 pulses of 10,000 G in each of the X, Y, and Z directions (IEC 68-2-27 Test Ea)	

#### NOTES:

Microphones meet all acoustic and electrical specifications before and after reliability testing, except sensitivity which can deviate up to 3dB.

After 3 reflow cycles, the sensitivity of the microphones shall not deviate more than 1 dB from its initial value.





## SPECIFICATION REVISIONS

Revision	Specification Changes	Date
А	Initial Release (ECR 19-3099)	6/27/19

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